Welcome to [E-XFL.COM](#)**Understanding [Embedded - CPLDs \(Complex Programmable Logic Devices\)](#)**

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

**Applications of Embedded - CPLDs****Details**

Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	12 ns
Voltage Supply - Internal	3V ~ 3.6V
Number of Logic Elements/Blocks	-
Number of Macrocells	384
Number of Gates	-
Number of I/O	192
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	256-LBGA
Supplier Device Package	256-SBGA (27x27)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/lattice-semiconductor/m4a3-384-192-12sai">https://www.e-xfl.com/product-detail/lattice-semiconductor/m4a3-384-192-12sai</a>

## GENERAL DESCRIPTION

The ispMACH™ 4A family from Lattice offers an exceptionally flexible architecture and delivers a superior Complex Programmable Logic Device (CPLD) solution of easy-to-use silicon products and software tools. The overall benefits for users are a guaranteed and predictable CPLD solution, faster time-to-market, greater flexibility and lower cost. The ispMACH 4A devices offer densities ranging from 32 to 512 macrocells with 100% utilization and 100% pin-out retention. The ispMACH 4A families offer 5-V (M4A5-xxx) and 3.3-V (M4A3-xxx) operation.

ispMACH 4A products are 5-V or 3.3-V in-system programmable through the JTAG (IEEE Std. 1149.1) interface. JTAG boundary scan testing also allows product testability on automated test equipment for device connectivity.

All ispMACH 4A family members deliver First-Time-Fit and easy system integration with pin-out retention after any design change and refit. For both 3.3-V and 5-V operation, ispMACH 4A products can deliver guaranteed fixed timing as fast as 5.0 ns  $t_{PD}$  and 182 MHz  $f_{CNT}$  through the SpeedLocking feature when using up to 20 product terms per output (Table 2).

**Table 2. ispMACH 4A Speed Grades**

Device	Speed Grade							
	-5	-55	-6	-65	-7	-10	-12	-14
M4A3-32	C				C, I	C, I	I	
M4A5-32								
M4A3-64/32		C			C, I	C, I	I	
M4A5-64/32								
M4A3-64/64		C			C, I	C, I	I	
M4A3-96		C			C, I	C, I	I	
M4A5-96								
M4A3-128		C			C, I	C, I	I	
M4A5-128								
M4A3-192			C		C, I	C, I	I	
M4A5-192								
M4A3-256/128		C		C	C, I	C, I	I	
M4A5-256/128				C	C	C, I	I	
M4A3-256/192					C	C, I	I	
M4A3-256/160								
M4A3-384				C		C, I	C, I	I
M4A3-512					C	C, I	C, I	I

**Note:**

1. C = Commercial    I = Industrial

**Table 4. Architectural Summary of ispMACH 4A devices**

ispMACH 4A Devices		
	M4A3-64/32, M4A5-64/32 M4A3-96/48, M4A5-96/48 M4A3-128/64, M4A5-128/64 M4A3-192/96, M4A5-192/96 M4A3-256/128, M4A5-256/128 M4A3-384 M4A3-512	M4A3-32/32 M4A5-32/32 M4A3-64/64 M4A3-256/160 M4A3-256/192
Macrocell-I/O Cell Ratio	2:1	1:1
Input Switch Matrix	Yes	Yes <sup>1</sup>
Input Registers	Yes	No
Central Switch Matrix	Yes	Yes
Output Switch Matrix	Yes	Yes

The Macrocell-I/O cell ratio is defined as the number of macrocells versus the number of I/O cells internally in a PAL block (Table 4).

The central switch matrix takes all dedicated inputs and signals from the input switch matrices and routes them as needed to the PAL blocks. Feedback signals that return to the same PAL block still must go through the central switch matrix. This mechanism ensures that PAL blocks in ispMACH 4A devices communicate with each other with consistent, predictable delays.

The central switch matrix makes a ispMACH 4A device more advanced than simply several PAL devices on a single chip. It allows the designer to think of the device not as a collection of blocks, but as a single programmable device; the software partitions the design into PAL blocks through the central switch matrix so that the designer does not have to be concerned with the internal architecture of the device.

Each PAL block consists of:

- ◆ Product-term array
- ◆ Logic allocator
- ◆ Macrocells
- ◆ Output switch matrix
- ◆ I/O cells
- ◆ Input switch matrix
- ◆ Clock generator

**Notes:**

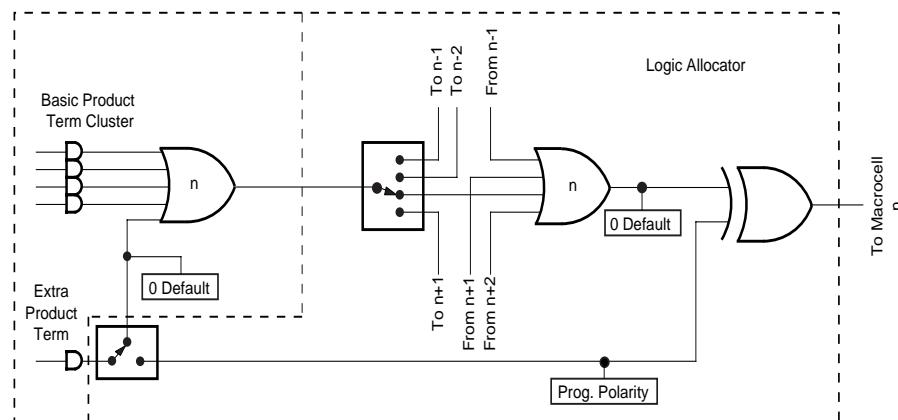
1. M4A3-64/64 internal switch matrix functionality embedded in central switch matrix.

**Table 6. Logic Allocator for All ispMACH 4A Devices (except M4A(3,5)-32/32)**

Output Macrocell	Available Clusters	Output Macrocell	Available Clusters
M <sub>0</sub>	C <sub>0</sub> , C <sub>1</sub> , C <sub>2</sub>	M <sub>8</sub>	C <sub>7</sub> , C <sub>8</sub> , C <sub>9</sub> , C <sub>10</sub>
M <sub>1</sub>	C <sub>0</sub> , C <sub>1</sub> , C <sub>2</sub> , C <sub>3</sub>	M <sub>9</sub>	C <sub>8</sub> , C <sub>9</sub> , C <sub>10</sub> , C <sub>11</sub>
M <sub>2</sub>	C <sub>1</sub> , C <sub>2</sub> , C <sub>3</sub> , C <sub>4</sub>	M <sub>10</sub>	C <sub>9</sub> , C <sub>10</sub> , C <sub>11</sub> , C <sub>12</sub>
M <sub>3</sub>	C <sub>2</sub> , C <sub>3</sub> , C <sub>4</sub> , C <sub>5</sub>	M <sub>11</sub>	C <sub>10</sub> , C <sub>11</sub> , C <sub>12</sub> , C <sub>13</sub>
M <sub>4</sub>	C <sub>3</sub> , C <sub>4</sub> , C <sub>5</sub> , C <sub>6</sub>	M <sub>12</sub>	C <sub>11</sub> , C <sub>12</sub> , C <sub>13</sub> , C <sub>14</sub>
M <sub>5</sub>	C <sub>4</sub> , C <sub>5</sub> , C <sub>6</sub> , C <sub>7</sub>	M <sub>13</sub>	C <sub>12</sub> , C <sub>13</sub> , C <sub>14</sub> , C <sub>15</sub>
M <sub>6</sub>	C <sub>5</sub> , C <sub>6</sub> , C <sub>7</sub> , C <sub>8</sub>	M <sub>14</sub>	C <sub>13</sub> , C <sub>14</sub> , C <sub>15</sub>
M <sub>7</sub>	C <sub>6</sub> , C <sub>7</sub> , C <sub>8</sub> , C <sub>9</sub>	M <sub>15</sub>	C <sub>14</sub> , C <sub>15</sub>

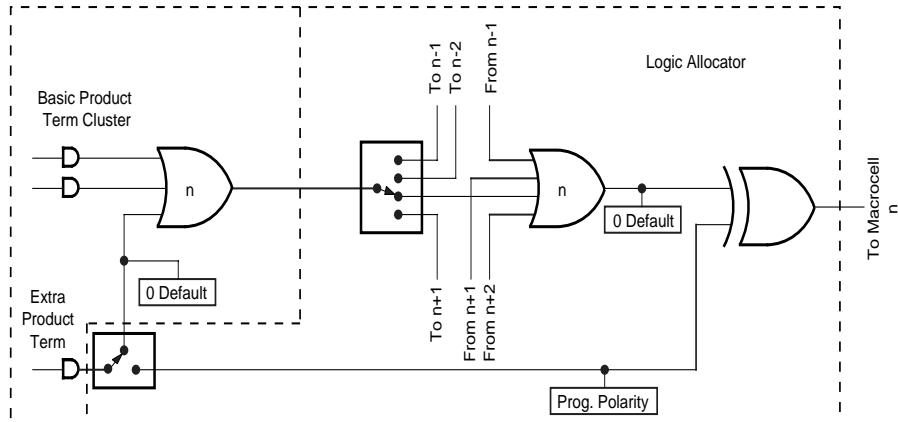
**Table 7. Logic Allocator for M4A(3,5)-32/32**

Output Macrocell	Available Clusters	Output Macrocell	Available Clusters
M <sub>0</sub>	C <sub>0</sub> , C <sub>1</sub> , C <sub>2</sub>	M <sub>8</sub>	C <sub>8</sub> , C <sub>9</sub> , C <sub>10</sub>
M <sub>1</sub>	C <sub>0</sub> , C <sub>1</sub> , C <sub>2</sub> , C <sub>3</sub>	M <sub>9</sub>	C <sub>8</sub> , C <sub>9</sub> , C <sub>10</sub> , C <sub>11</sub>
M <sub>2</sub>	C <sub>1</sub> , C <sub>2</sub> , C <sub>3</sub> , C <sub>4</sub>	M <sub>10</sub>	C <sub>9</sub> , C <sub>10</sub> , C <sub>11</sub> , C <sub>12</sub>
M <sub>3</sub>	C <sub>2</sub> , C <sub>3</sub> , C <sub>4</sub> , C <sub>5</sub>	M <sub>11</sub>	C <sub>10</sub> , C <sub>11</sub> , C <sub>12</sub> , C <sub>13</sub>
M <sub>4</sub>	C <sub>3</sub> , C <sub>4</sub> , C <sub>5</sub> , C <sub>6</sub>	M <sub>12</sub>	C <sub>11</sub> , C <sub>12</sub> , C <sub>13</sub> , C <sub>14</sub>
M <sub>5</sub>	C <sub>4</sub> , C <sub>5</sub> , C <sub>6</sub> , C <sub>7</sub>	M <sub>13</sub>	C <sub>12</sub> , C <sub>13</sub> , C <sub>14</sub> , C <sub>15</sub>
M <sub>6</sub>	C <sub>5</sub> , C <sub>6</sub> , C <sub>7</sub>	M <sub>14</sub>	C <sub>13</sub> , C <sub>14</sub> , C <sub>15</sub>
M <sub>7</sub>	C <sub>6</sub> , C <sub>7</sub>	M <sub>15</sub>	C <sub>14</sub> , C <sub>15</sub>



a. Synchronous Mode

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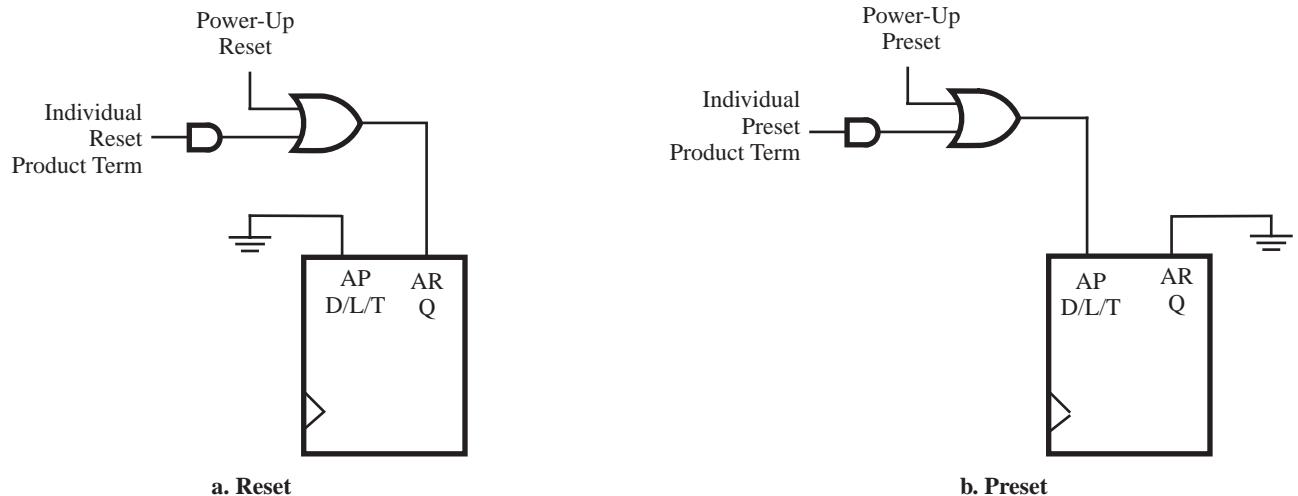


b. Asynchronous Mode

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**Figure 2. Logic Allocator: Configuration of Cluster "n" Set by Mode of Macrocell "n"**

A reset/preset swapping feature in each macrocell allows for reset and preset to be exchanged, providing flexibility. In asynchronous mode (Figure 8), a single individual product term is provided for initialization. It can be selected to control reset or preset.



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17466G-015

**Figure 8. Asynchronous Mode Initialization Configurations**

Note that the reset/preset swapping selection feature effects power-up reset as well. The initialization functionality of the flip-flops is illustrated in Table 9. The macrocell sends its data to the output switch matrix and the input switch matrix. The output switch matrix can route this data to an output if so desired. The input switch matrix can send the signal back to the central switch matrix as feedback.

**Table 9. Asynchronous Reset/Preset Operation**

AR	AP	CLK/LE <sup>1</sup>	Q+
0	0	X	See Table 8
0	1	X	1
1	0	X	0
1	1	X	0

**Note:**

1. Transparent latch is unaffected by AR, AP

## IEEE 1149.1-COMPLIANT BOUNDARY SCAN TESTABILITY

All ispMACH 4A devices have boundary scan cells and are compliant to the IEEE 1149.1 standard. This allows functional testing of the circuit board on which the device is mounted through a serial scan path that can access all critical logic nodes. Internal registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test node data to be captured and shifted out for verification. In addition, these devices can be linked into a board-level serial scan path for more complete board-level testing.

## IEEE 1149.1-COMPLIANT IN-SYSTEM PROGRAMMING

Programming devices in-system provides a number of significant benefits including: rapid prototyping, lower inventory levels, higher quality, and the ability to make in-field modifications. All ispMACH 4A devices provide In-System Programming (ISP) capability through their Boundary ScanTest Access Ports. This capability has been implemented in a manner that ensures that the port remains compliant to the IEEE 1149.1 standard. By using IEEE 1149.1 as the communication interface through which ISP is achieved, customers get the benefit of a standard, well-defined interface.

ispMACH 4A devices can be programmed across the commercial temperature and voltage range. The PC-based ispVM™ software facilitates in-system programming of ispMACH 4A devices. ispVM takes the JEDEC file output produced by the design implementation software, along with information about the JTAG chain, and creates a set of vectors that are used to drive the JTAG chain. ispVM software can use these vectors to drive a JTAG chain via the parallel port of a PC. Alternatively, ispVM software can output files in formats understood by common automated test equipment. This equipment can then be used to program ispMACH 4A devices during the testing of a circuit board.

## PCI COMPLIANT

ispMACH 4A devices in the -5/-55/-6/-65/-7/-10/-12 speed grades are compliant with the *PCI Local Bus Specification* version 2.1, published by the PCI Special Interest Group (SIG). The 5-V devices are fully PCI-compliant. The 3.3-V devices are mostly compliant but do not meet the PCI condition to clamp the inputs as they rise above  $V_{CC}$  because of their 5-V input tolerant feature.

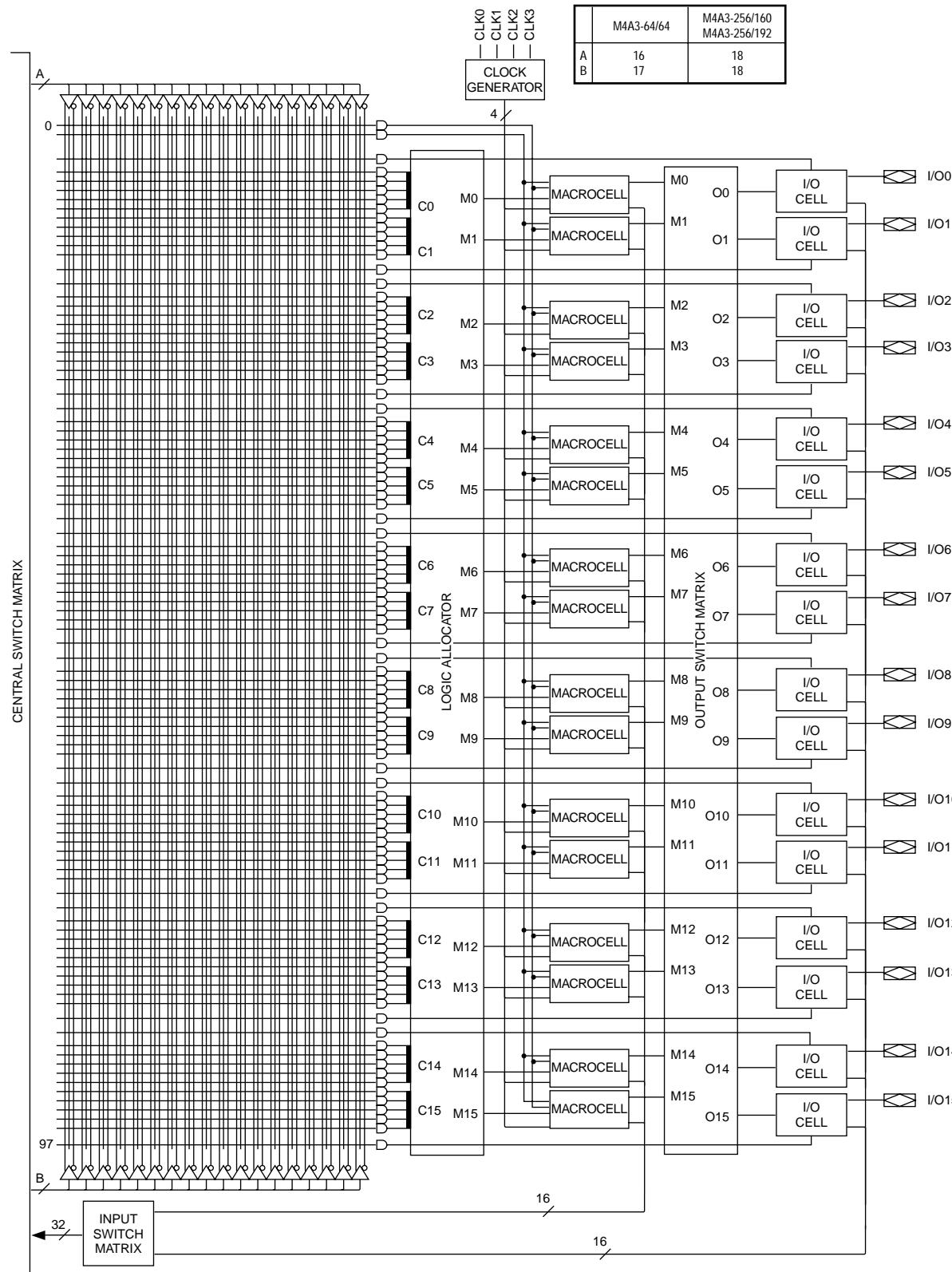
## SAFE FOR MIXED SUPPLY VOLTAGE SYSTEM DESIGNS

Both the 3.3-V and 5-V  $V_{CC}$  ispMACH 4A devices are safe for mixed supply voltage system designs. The 5-V devices will not overdrive 3.3-V devices above the output voltage of 3.3 V, while they accept inputs from other 3.3-V devices. The 3.3-V device will accept inputs up to 5.5 V. Both the 5-V and 3.3-V versions have the same high-speed performance and provide easy-to-use mixed-voltage design capability.

## PULL UP OR BUS-FRIENDLY INPUTS AND I/Os

All ispMACH 4A devices have inputs and I/Os which feature the Bus-Friendly circuitry incorporating two inverters in series which loop back to the input. This double inversion weakly holds the input at its last driven logic state. While it is good design practice to tie unused pins to a known state, the Bus-Friendly input structure pulls pins away from the input threshold voltage where noise can cause high-frequency switching. At power-up, the Bus-Friendly latches are reset to a logic level “1.” For the circuit diagram, please refer to the document entitled *MACH Endurance Characteristics* on the Lattice Data Book CD-ROM or Lattice web site.

All ispMACH 4A devices have a programmable bit that configures all inputs and I/Os with either pull-up or Bus-Friendly characteristics. If the device is configured in pull-up mode, all inputs and I/O pins are



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Figure 17. PAL Block for ispMACH 4A Devices with 1:1 Macrocell-I/O Cell Ratio (except M4A (3,5)-32/32)

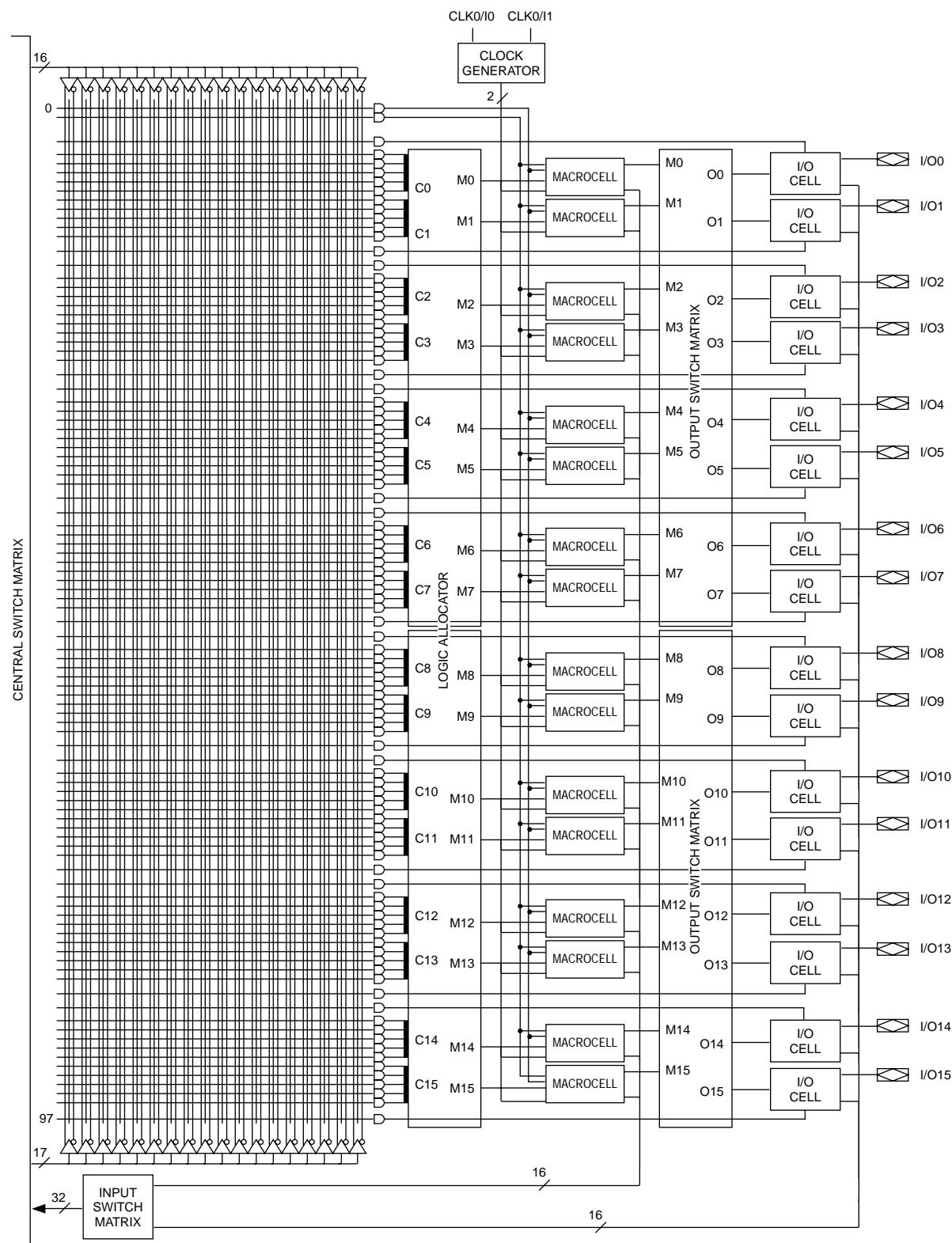
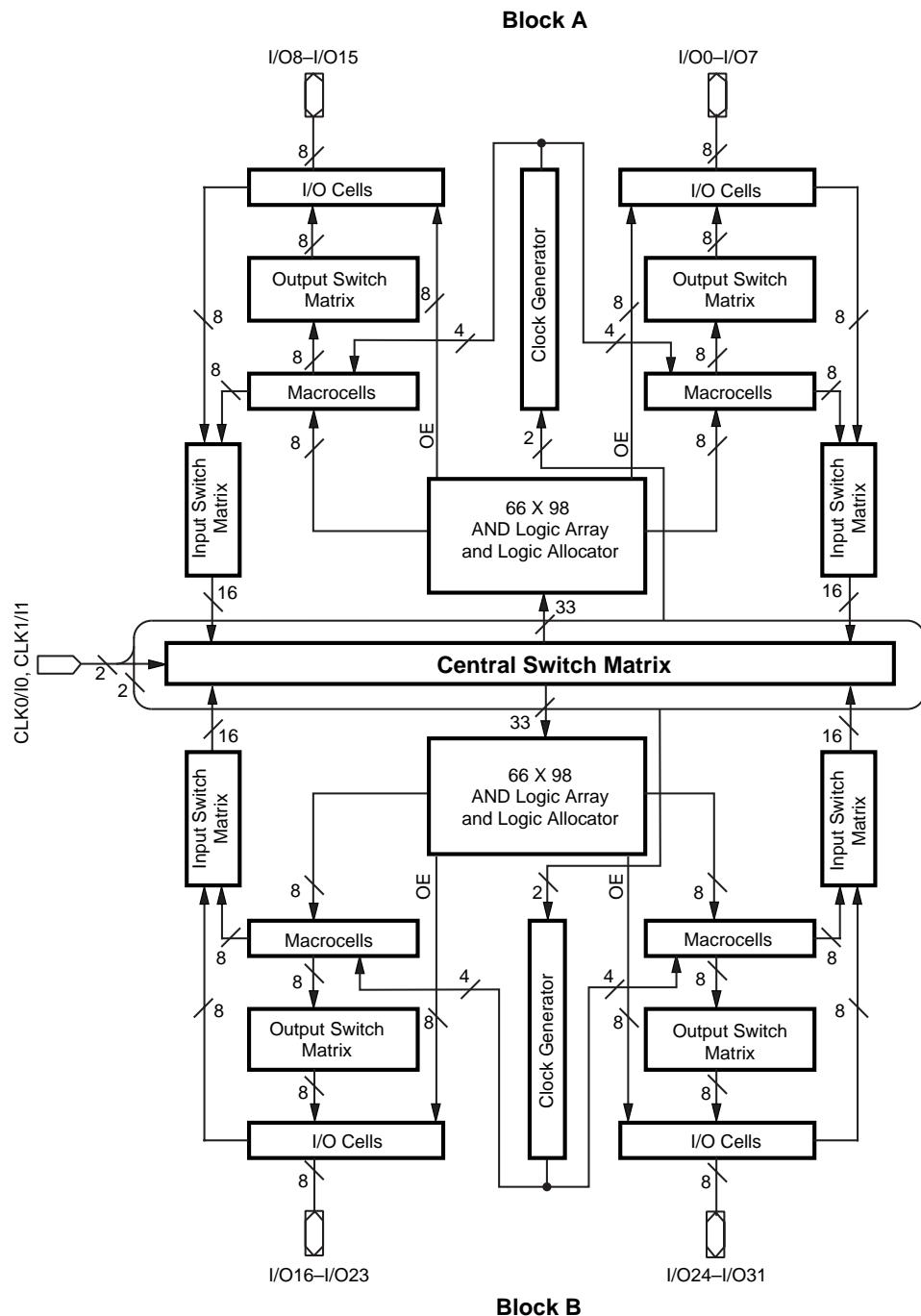


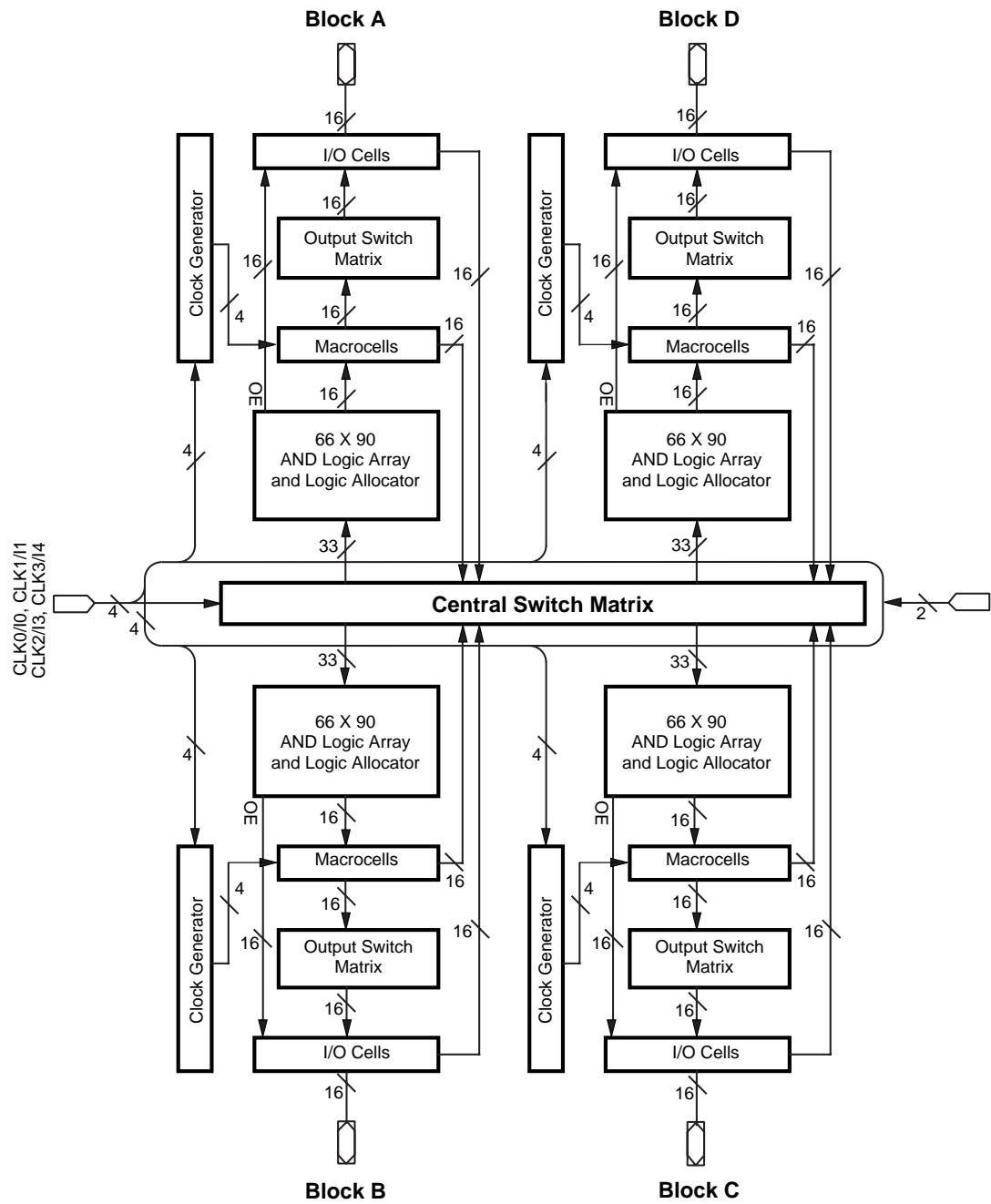
Figure 18. PAL Block for M4A (3,5)-32/32

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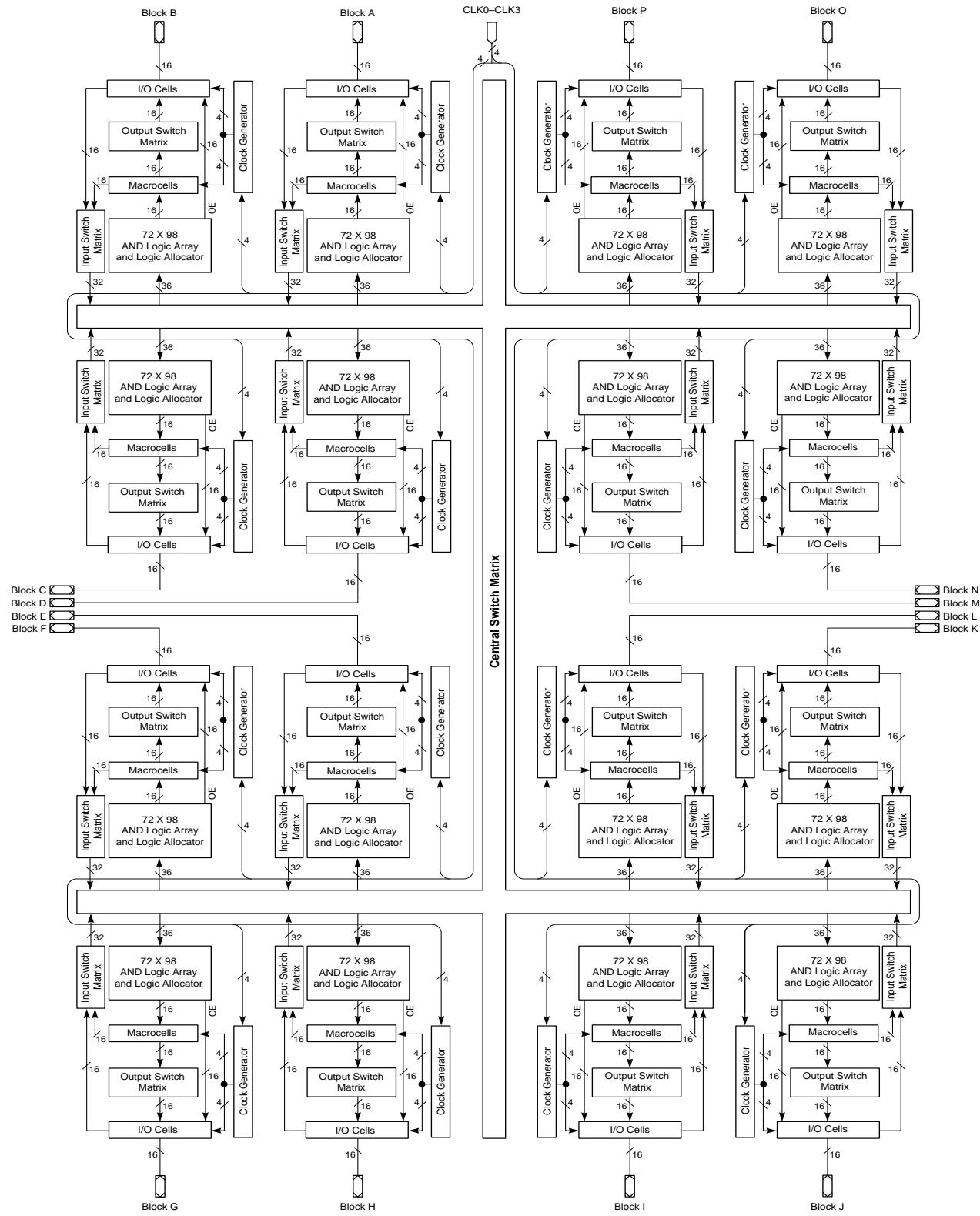
## BLOCK DIAGRAM – M4A(3,5)-32/32



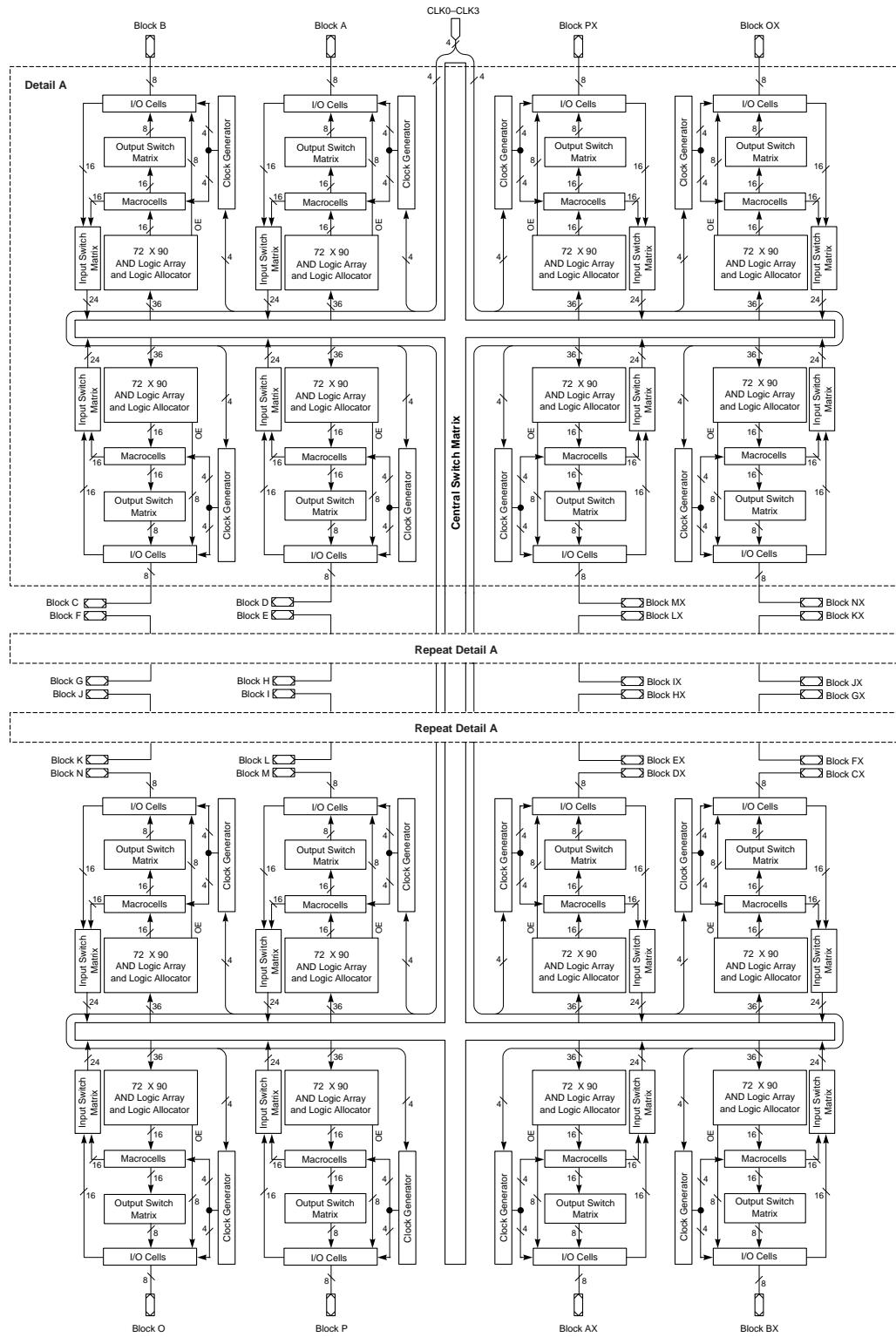
## BLOCK DIAGRAM – M4A3-64/64



## BLOCK DIAGRAM – M4A3-256/160, M4A3-256/192



## BLOCK DIAGRAM - M4A3-512/160, M4A3-512/192, M4A3-512/256



17466G-068

## ABSOLUTE MAXIMUM RATINGS

### M4A5

Storage Temperature.....	-65°C to +150°C
Ambient Temperature with Power Applied.....	-55°C to +100°C
Device Junction Temperature.....	+130°C
Supply Voltage with Respect to Ground .....	-0.5 V to +7.0 V
DC Input Voltage .....	-0.5 V to $V_{CC}$ + 0.5 V
Static Discharge Voltage.....	2000 V
Latchup Current ( $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$ ) .....	200 mA
<i>Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability.</i>	

## OPERATING RANGES

### Commercial (C) Devices

Ambient Temperature ( $T_A$ )	
Operating in Free Air.....	0°C to +70°C
Supply Voltage ( $V_{CC}$ ) with Respect to Ground.....	+4.75 V to +5.25 V

### Industrial (I) Devices

Ambient Temperature ( $T_A$ )	
Operating in Free Air.....	-40°C to +85°C
Supply Voltage ( $V_{CC}$ ) with Respect to Ground.....	+4.50 V to +5.5 V
<i>Operating ranges define those limits between which the functionality of the device is guaranteed.</i>	

## 5-V DC CHARACTERISTICS OVER OPERATING RANGES

Parameter Symbol	Parameter Description	Test Conditions	Min	Typ	Max	Unit
$V_{OH}$	Output HIGH Voltage	$I_{OH} = -3.2 \text{ mA}$ , $V_{CC} = \text{Min}$ , $V_{IN} = V_{IH}$ or $V_{IL}$	2.4			V
		$I_{OH} = -100 \mu\text{A}$ , $V_{CC} = \text{Max}$ , $V_{IN} = V_{IH}$ or $V_{IL}$		3.3	3.6	V
$V_{OL}$	Output LOW Voltage	$I_{OL} = 24 \text{ mA}$ , $V_{CC} = \text{Min}$ , $V_{IN} = V_{IH}$ or $V_{IL}$ (Note 1)			0.5	V
$V_{IH}$	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs (Note 2)	2.0			V
$V_{IL}$	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs (Note 2)			0.8	V
$I_{IH}$	Input HIGH Leakage Current	$V_{IN} = 5.25 \text{ V}$ , $V_{CC} = \text{Max}$ (Note 3)			10	$\mu\text{A}$
$I_{IL}$	Input LOW Leakage Current	$V_{IN} = 0 \text{ V}$ , $V_{CC} = \text{Max}$ (Note 3)			-10	$\mu\text{A}$
$I_{OZH}$	Off-State Output Leakage Current HIGH	$V_{OUT} = 5.25 \text{ V}$ , $V_{CC} = \text{Max}$ , $V_{IN} = V_{IH}$ or $V_{IL}$ (Note 3)			10	$\mu\text{A}$
$I_{OZL}$	Off-State Output Leakage Current LOW	$V_{OUT} = 0 \text{ V}$ , $V_{CC} = \text{Max}$ , $V_{IN} = V_{IH}$ or $V_{IL}$ (Note 3)			-10	$\mu\text{A}$
$I_{SC}$	Output Short-Circuit Current	$V_{OUT} = 0.5 \text{ V}$ , $V_{CC} = \text{Max}$ (Note 4)	-30		-160	mA

### Notes:

1. Total  $I_{OL}$  for one PAL block should not exceed 64 mA.
2. These are absolute values with respect to device ground, and all overshoots due to system or tester noise are included.
3. I/O pin leakage is the worst case of  $I_{IL}$  and  $I_{OZL}$  (or  $I_{IH}$  and  $I_{OZH}$ ).
4. Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second.  $V_{OUT} = 0.5 \text{ V}$  has been chosen to avoid test problems caused by tester ground degradation.

## ABSOLUTE MAXIMUM RATINGS

### M4A3

Storage Temperature .....	-65°C to +150°C
Ambient Temperature with Power Applied.....	-55°C to +100°C
Device Junction Temperature.....	+130°C
Supply Voltage with Respect to Ground .....	-0.5 V to +4.5 V
DC Input Voltage .....	-0.5 V to 6.0 V
Static Discharge Voltage.....	2000 V
Latchup Current ( $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$ ) .....	200 mA
<i>Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability.</i>	

## OPERATING RANGES

### Commercial (C) Devices

Ambient Temperature ( $T_A$ )	
Operating in Free Air.....	0°C to +70°C
Supply Voltage ( $V_{CC}$ ) with Respect to Ground.....	+3.0 V to +3.6 V

### Industrial (I) Devices

Ambient Temperature ( $T_A$ )	
Operating in Free Air.....	-40°C to +85°C
Supply Voltage ( $V_{CC}$ ) with Respect to Ground.....	+3.0 V to +3.6 V
<i>Operating ranges define those limits between which the functionality of the device is guaranteed.</i>	

## 3.3-V DC CHARACTERISTICS OVER OPERATING RANGES

Parameter Symbol	Parameter Description	Test Conditions	Min	Typ	Max	Unit
$V_{OH}$	Output HIGH Voltage	$V_{CC} = \text{Min}$ $V_{IN} = V_{IH}$ or $V_{IL}$	$I_{OH} = -100 \mu\text{A}$	$V_{CC} - 0.2$		V
			$I_{OH} = -3.2 \text{ mA}$	2.4		V
$V_{OL}$	Output LOW Voltage	$V_{CC} = \text{Min}$ $V_{IN} = V_{IH}$ or $V_{IL}$ (Note 1)	$I_{OL} = 100 \mu\text{A}$		0.2	V
			$I_{OL} = 24 \text{ mA}$		0.5	V
$V_{IH}$	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs	2.0		5.5	V
$V_{IL}$	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs	-0.3		0.8	V
$I_{IH}$	Input HIGH Leakage Current	$V_{IN} = 3.6 \text{ V}$ , $V_{CC} = \text{Max}$ (Note 2)			5	$\mu\text{A}$
$I_{IL}$	Input LOW Leakage Current	$V_{IN} = 0 \text{ V}$ , $V_{CC} = \text{Max}$ (Note 2)			-5	$\mu\text{A}$
$I_{OZH}$	Off-State Output Leakage Current HIGH	$V_{OUT} = 3.6 \text{ V}$ , $V_{CC} = \text{Max}$ $V_{IN} = V_{IH}$ or $V_{IL}$ (Note 2)			5	$\mu\text{A}$
$I_{OZL}$	Off-State Output Leakage Current LOW	$V_{OUT} = 0 \text{ V}$ , $V_{CC} = \text{Max}$ $V_{IN} = V_{IH}$ or $V_{IL}$ (Note 2)			-5	$\mu\text{A}$
$I_{SC}$	Output Short-Circuit Current	$V_{OUT} = 0.5 \text{ V}$ , $V_{CC} = \text{Max}$ (Note 3)	-15		-160	mA

### Notes:

1. Total  $I_{OL}$  for one PAL block should not exceed 64 mA.
2. I/O pin leakage is the worst case of  $I_{IL}$  and  $I_{OZL}$  (or  $I_{IH}$  and  $I_{OZH}$ ).
3. Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second.

### Notes:

1. See "MACH Switching Test Circuit" document on the Literature Download page of the Lattice web site.
2. This parameter does not apply to flip-flops in the emulated mode since the feedback path is required for emulation.

## ispMACH 4A TIMING PARAMETERS OVER OPERATING RANGES<sup>1</sup>

		-5		-55		-6		-65		-7		-10		-12		-14		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
<b>Frequency:</b>																		
$f_{MAXS}$	External feedback, D-type, Min of $1/(t_{WLS} + t_{WHS})$ or $1/(t_{SS} + t_{COS})$	143		133		125		118		95.2		87.0		74.1		60.6		MHz
	External feedback, T-type, Min of $1/(t_{WLS} + t_{WHS})$ or $1/(t_{SST} + t_{COS})$	125		125		118		111		87.0		80.0		69.0		57.1		MHz
	Internal feedback ( $f_{CNT}$ ), D-type, Min of $1/(t_{WLS} + t_{WHS})$ or $1/(t_{SS} + t_{COS})$	182		167		160		154		125		118		95.0		74.1		MHz
	Internal feedback ( $f_{CNT}$ ), T-type, Min of $1/(t_{WLS} + t_{WHS})$ or $1/(t_{SST} + t_{COS})$	154		154		148		143		111		105		87.0		69.0		MHz
	No feedback <sup>2</sup> , Min of $1/(t_{WLS} + t_{WHS})$ , $1/(t_{SS} + t_{HS})$ or $1/(t_{SST} + t_{HS})$	250		250		200		200		154		125		100		83.3		MHz
$f_{MAXA}$	External feedback, D-type, Min of $1/(t_{WLA} + t_{WHA})$ or $1/(t_{SA} + t_{COA})$	111		111		108		100		83.3		66.7		55.6		43.5		MHz
	External feedback, T-type, Min of $1/(t_{WLA} + t_{WHA})$ or $1/(t_{SAT} + t_{COA})$	105		105		102		95.2		76.9		62.5		52.6		41.7		MHz
	Internal feedback ( $f_{CNTA}$ ), D-type, Min of $1/(t_{WLA} + t_{WHA})$ or $1/(t_{SA} + t_{COA})$	133		133		125		125		105		83.3		66.7		50.0		MHz
	Internal feedback ( $f_{CNTA}$ ), T-type, Min of $1/(t_{WLA} + t_{WHA})$ or $1/(t_{SAT} + t_{COA})$	125		125		125		118		95.2		76.9		62.5		47.6		MHz
	No feedback <sup>2</sup> , Min of $1/(t_{WLA} + t_{WHA})$ , $1/(t_{SA} + t_{HA})$ or $1/(t_{SAT} + t_{HA})$	167		167		143		143		125		100		62.5		55.6		MHz
$f_{MAXI}$	Maximum input register frequency, Min of $1/(t_{WIRH} + t_{WIRL})$ or $1/(t_{SIRS} + t_{HIRS})$	167		167		143		143		125		100		83.3		83.3		MHz

**Notes:**

- See "Switching Test Circuit" document on the Literature Download page of the Lattice web site.
- This parameter does not apply to flip-flops in the emulated mode since the feedback path is required for emulation.

## CAPACITANCE<sup>1</sup>

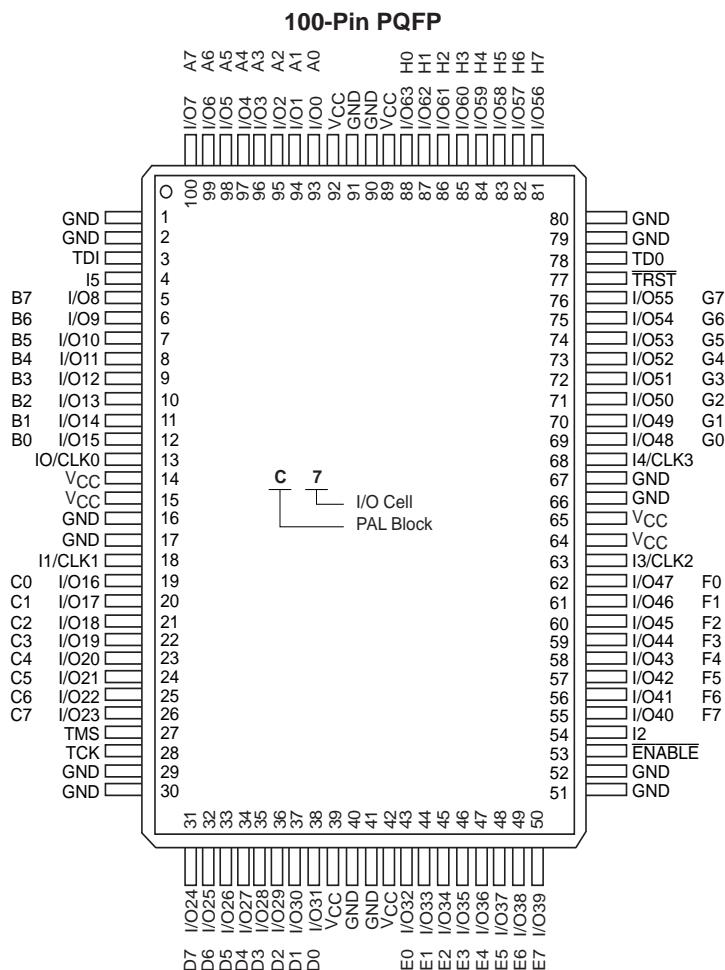
Parameter Symbol	Parameter Description	Test Conditions		Typ	Unit
$C_{IN}$	Input capacitance	$V_{IN}=2.0\text{ V}$	3.3 V or 5 V, 25°C, 1 MHz	6	pF
$C_{I/O}$	Output capacitance	$V_{OUT}=2.0\text{ V}$	3.3 V or 5 V, 25°C, 1 MHz	8	pF

**Note:**

- These parameters are not 100% tested, but are calculated at initial characterization and at any time the design is modified where this parameter may be affected.

## 100-PIN PQFP CONNECTION DIAGRAM (M4A(3,5)-128/64)

### Top View



17466G-031

### PIN DESIGNATIONS

I/CLK = Input or Clock

GND = Ground

I = Input

I/O = Input/Output

V<sub>CC</sub> = Supply Voltage

TDI = Test Data In

TCK = Test Clock

TMS = Test Mode Select

TDO = Test Data Out

TRST = Test Reset

ENABLE = Program

## 100-BALL caBGA CONNECTION DIAGRAM (M4A3-128/64)

### Bottom View

100-Ball caBGA

	10	9	8	7	6	5	4	3	2	1	
A	GND	I/O63 H7	I/O60 H4	I/O57 H1	GND	GND	I/O1 A1	I/O4 A4	I/O7 A7	GND	A
B	TRST	GND	I/O61 H5	I5	VCC	I/O0 A0	I/O6 A6	GND	TDI	I/O15 B7	B
C	I/O53 G5	TDO	I/O62 H6	I/O58 H2	I/O56 H0	I/O2 A2	GND	I/O14 B6	I/O13 B5	I/O12 B4	C
D	I/O50 G2	I/O55 G7	GND	I/O59 H3	I/O3 A3	I/O5 A5	I/O11 B3	I/O10 B2	CLK0/I0	I/O9 B1	D
E	CLK3/I4	I/O49 G1	I/O51 G3	I/O54 G6	VCC	I/O16 C0	I/O20 C4	I/O8 B0	VCC	GND	E
F	GND	VCC	I/O40 F0	I/O52 G4	I/O48 G0	VCC	I/O22 C6	I/O19 C3	I/O17 C1	CLK1/I1	F
G	I/O41 F1	CLK2/I3	I/O42 F2	I/O43 F3	I/O37 E5	I/O35 E3	I/O27 D3	GND	I/O23 C7	I/O18 C2	G
H	I/O44 F4	I/O45 F5	I/O46 F6	GND	I/O34 E2	I/O24 D0	I/O26 D2	I/O30 D6	TCK	I/O21 C5	H
J	I/O47 F7	ENABLE	GND	I/O38 E6	I/O32 E0	VCC	I2	I/O29 D5	GND	TMS	J
K	GND	I/O39 E7	I/O36 E4	I/O33 E1	GND	GND	I/O25 D1	I/O28 D4	I/O31 D7	GND	K

10      9      8      7      6      5      4      3      2      1

### PIN DESIGNATIONS

CLK	= Clock
GND	= Ground
I	= Input
I/O	= Input/Output
N/C	= No Connect
VCC	= Supply Voltage
TDI	= Test Data In
TCK	= Test Clock
TMS	= Test Mode Select
TDO	= Test Data Out
TRST	= Test Reset
ENABLE	= Program



17466G-100cabga

## 144-BALL FPBGA CONNECTION DIAGRAM (M4A3-192/96)

### Bottom View

144-Ball fpBGA

	12	11	10	9	8	7	6	5	4	3	2	1	
A	GND	I/O72 L7	I/O76 L3	I13	GBCLK3	I0	I/O82 A2	I/O86 A6	I/O88 B0	I/O93 B5	I/O95 B7	GND	A
B	GND	I/O73 L6	I/O77 L2	I/O79 L0	VCC	I1	I/O83 A3	I/O87 A7	I/O90 B2	I/O94 B6	I/O0 D7	TDI	B
C	GND	TDO	I/O74 L5	I14	GND	I/O80 A0	I/O84 A4	GND	I/O92 B4	I/O1 D6	I/O4 D3	I/O3 D4	C
D	I/O67 K4	I/O69 K2	I/O71 K0	I/O75 L4	GBCLK0	I/O81 A1	VCC	I/O91 B3	I/O2 D5	I2	I/O6 D1	I/O7 D0	D
E	I12	I/O64 K7	I/O66 K5	I/O70 K1	I/O78 L1	I/O85 A5	I/O89 B1	I/O5 D2	I/O8 C7	I4	GND	VCC	E
F	I10	I11	GND	I/O65 K6	I/O68 K3	I15	I3	GND	I/O12 C3	I/O11 C4	I/O10 C5	I/O9 C6	F
G	I/O60 J3	I/O61 J2	I/O62 J1	I/O63 J0	VCC	GND	I7	I/O20 E3	I/O17 E6	I/O15 C0	I/O14 C1	I/O13 C2	G
H	I/O56 J7	I/O57 J6	I/O58 J5	I/O59 J4	I/O53 I2	I/O41 H1	I/O37 G5	I/O30 F1	I/O22 E1	I/O18 E5	I/O16 E7	VCC	H
J	I/O55 I0	I/O54 I1	VCC	I/O50 I5	I/O43 H3	VCC	I/O33 G1	GBCLK2	I/O27 F4	I/O23 E0	I/O21 E2	I/O19 E4	J
K	I/O51 I4	I/O52 I3	I/O49 I6	I/O44 H4	GND	I/O36 G4	I/O32 G0	VCC	I6	I/O26 F5	TCK	TMS	K
L	GND	I/O48 I7	I/O46 H6	I/O42 H2	I/O39 G7	I/O35 G3	I9	GND	I/O31 F0	I/O29 F2	I/O25 F6	GND	L
M	GND	I/O47 H7	I/O45 H5	I/O40 H0	I/O38 G6	I/O34 G2	I8	GBCLK1	I5	I/O28 F3	I/O24 F7	GND	M

### PIN DESIGNATIONS

CLK = Clock  
 GND = Ground  
 I = Input  
 I/O = Input/Output  
 N/C = No Connect  
 VCC = Supply Voltage  
 TDI = Test Data In  
 TCK = Test Clock  
 TMS = Test Mode Select  
 TDO = Test Data Out



## 256-BALL fpBGA CONNECTION DIAGRAM (M4A3-256/192)

### Bottom View

256-Ball fpBGA

	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	
A	I/O167 N15	I/O181 O13	I/O180 O12	I/O177 O9	I/O174 O6	I/O172 O4	I/O191 P14	I/O186 P4	I/O1 A2	I/O3 A6	GCLK0	I/O9 B1	I/O13 B5	I/O15 B7	I/O18 B10	I/O20 B12 <th>A</th>	A
B	I/O165 N13	I/O166 N14	I/O182 O14	I/O179 O11	I/O175 O7	I/O173 O5	I/O168 O0	I/O187 P6	I/O0 A0	I/O5 A10	I/O7 A14	I/O10 B2	I/O16 B8	I/O19 B11	I/O21 B13	NC	B
C	I/O163 N11	I/O164 N12	NC	I/O183 O15	I/O178 O10	I/O170 O2	I/O171 O3	I/O189 P10	I/O184 P0	I/O6 A12	I/O12 B4	I/O14 B6	I/O23 B15	I/O22 B14	TDI	I/O39 C15	C
D	I/O158 N6	I/O159 N7	TDO	GND	GND	VCC	GND	VCC	GND	GND	VCC	GND	VCC	I/O17 B9	I/O38 C14	I/O37 C13	D
E	I/O156 N4	NC	I/O162 N10	VCC	I/O160 N8	I/O161 N9	I/O190 P12	GCLK3	I/O188 P8	I/O2 A4	I/O8 B0	NC	GND	I/O36 C12	I/O35 C11	I/O31 C7	E
F	I/O152 N0	I/O157 N5	I/O155 N3	GND	I/O154 N2	I/O153 N1	I/O176 O8	I/O169 O1	I/O185 P2	I/O4 A8	I/O11 B3	I/O34 C10	VCC	I/O32 C8	I/O30 C6	I/O29 C5	F
G	I/O147 M6	I/O150 M12	I/O149 M10	VCC	I/O148 M8	I/O151 M14	VCC	GND	GND	VCC	I/O33 C9	I/O28 C4	GND	I/O26 C2	I/O25 C1	I/O47 D14	G
H	I/O144 M0	I/O146 M4	I/O145 OM2	GND	I/O136 L0	I/O137 L2	GND	VCC	VCC	GND	I/O27 C3	I/O24 C0	VCC	I/O44 D8	I/O43 D6	I/O42 D4	H
J	I/O138 L4	I/O139 L6	I/O140 L8	GND	I/O142 L12	I/O141 L10	GND	VCC	VCC	GND	I/O46 D12	I/O45 D10	GND	I/O49 E2	I/O48 E0	I/O50 E4	J
K	I/O143 L14	I/O120 K0	I/O121 K1	VCC	I/O123 K3	I/O122 K2	VCC	GND	GND	VCC	I/O41 D2	I/O40 D0	VCC	I/O55 E14	I/O54 E12	I/O56 F0	K
L	I/O124 K4	I/O125 K5	I/O127 K7	GND	I/O130 K10	I/O126 K6	I/O98 I4	I/O91 H6	I/O75 G3	I/O77 G5	I/O52 E8	I/O51 E6	GND	I/O59 F3	I/O60 F4	I/O57 F1	L
M	I/O128 K8	I/O129 K9	I/O131 K11	GND	I/O107 J3	I/O105 J1	I/O100 I8	I/O90 H4	I/O74 G2	I/O80 G8	I/O83 G11	I/O53 E10	VCC	I/O68 F12	I/O63 F7	I/O58 F2	M
N	I/O132 K12	I/O133 K13	I/O135 K15	VCC	GND	VCC	GND	VCC	GND	VCC	GND	GND	TCK	I/O64 F8	I/O61 F5	N	
P	I/O134 K14	I/O117 J13	I/O118 J14	I/O119 J15	I/O108 J4	I/O106 J2	I/O101 I10	I/O89 H2	I/O93 H10	I/O94 H12	I/O79 G7	I/O84 G12	I/O87 G15	TMS	I/O65 F9	I/O62 F6	P
R	I/O116 J12	I/O115 J11	I/O112 J8	I/O111 J7	I/O104 J0	I/O102 I12	I/O99 I6	I/O96 I0	I/O92 H8	I/O72 G0	I/O76 G4	I/O81 G9	I/O85 G13	I/O71 F15	I/O67 F11	I/O66 F10	R
T	I/O114 J10	I/O113 J9	I/O110 J6	I/O109 J5	I/O103 I14	GCLK2	I/O97 I2	I/O88 H0	GCLK1	I/O95 H14	I/O73 G1	I/O78 G6	I/O82 G10	I/O86 G14	I/O70 F14	I/O69 F13	T

### PIN DESIGNATIONS

CLK	= Clock
GND	= Ground
I	= Input
I/O	= Input/Output
N/C	= No Connect
VCC	= Supply Voltage
TDI	= Test Data In
TCK	= Test Clock
TMS	= Test Mode Select
TDO	= Test Data Out



17466G-047



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## Revision History

Date	Version	Change Summary
-	K	Previous Lattice release.
August 2006	L	Updated for lead-free package options.
September 2006	M	Revised M4A3-256/160 208-pin PQFP connection diagram.